Braskem

Data Sheet

Linear Low Density Polyethylene IC32

Description:
IC32 is a linear low-density polyethylene, with narrow molecular weight, produced by solution process, for injection molding. It offers good fluidity, excellent flexibility, tenacity and low warpage. It contains special antioxidant additives.

Application:
Resin has been specifically developed for lids molding injection, house appliances and master batch production.

Control Properties:

	ASTM Methods	Units	Values
Melt Flow Rate (190/2.16)	D 1238	g/10 min	29
Density	D 729	g/cm³	0.924

Typical Properties:
Plaque Properties[a]

	ASTM Methods	Units	Values
Tensile Strength at Yield	D 638	MPa	12
Tensile Strength at Break	D 638	MPa	9
Tensile Modulus – 1% Secant	D 790	MPa	350
Tensile Elongation at Break	D 638	%	250
Environmental Stress Cracking Resistanceb	D 1693	h/F50	-
Vicat Softening Temperature at 10 N	D 1525	°C	1
Rigidity	D 747	MPa	320
Fragility Temperature	D 746	ºC	<-70

(a) Test specimens prepared from compression molded sheet made according to ASTM D 4703.
(b) Compression molded 2 mm thickness, 0.3 mm notched-plaques; 10% Igepal; 50ºC.

Recommended Processing Conditions:
The IC32 resin has been developed to be used in injection molding, in similar conditions to the other Linear Low Density Polyethylene of similar fluidity.
Recommended temperature profile: 150 to 200ºC.